

VFH2321-VFH2324

VFH2421-VFH2424

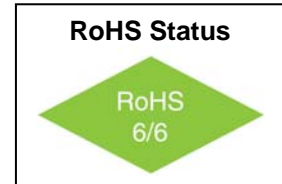
XO Hi-REL, 1.8V

5x7mm SMD, HCMOS



Features

- Leadless chip carrier package is hermetically sealed for superior aging and field performance
- Crystal angle controlled to ± 0.5 minute for excellent temperature stability
- 168 hour Class B burn-in and extensive environmental testing for best performance in rugged field environments
- Guarantee start-up with a ramping DC supply
- Start-up time <5ms, typical
- Tristate option available
- Calculated MTBF is 3.8×10^6 hours at 125°C



Description

These high reliability oscillators provide HCMOS clock waveforms for applications subjected to the most stringent environmental conditions. They are mechanically robust and weigh less than 0.2 grams. This 5x7 mm SMD package has a hermetic seal, thus ensuring the integrity of each oscillator. Each oscillator is burned-in at 125°C for 168 hours, temperature cycled and centrifuged then fully tested in accordance with Table 1. Reliability tests are performed per Table 2. The calculated MTBF is 3.8×10^6 at 125°C.

Electrical Specifications

Parameter	Symbol	Condition	Min	Typ	Max	Unit	Note
Frequency Range	F		0.85		165	MHz	
Frequency Stability	$\Delta F/F$	Vs. Operating Temperature	± 25		± 75	ppm	See Chart
		Aging 1 st Year After 1 st Year			± 3 ± 1		
Operating Temperature Range	T		-55°		+125°	°C	See Chart
Input Voltage	V _{cc}		1.7	1.8	1.9	V	
Input Current	I _{cc}	850 KHz to 70 MHz, with 15pF load 70.1 to 165.0 MHz with 15pF load		7.0 15.0	10.0 18.0	mA	
Jitter RMS					10	ps	
Waveform Symmetry		Measured at 50% V _{DD} 850 KHz to 70 MHz 70.1 to 165.0 MHz		48/52 45/55	45/55 40/60	%	
Rise / Fall Time	Tr/Tf				5	ns	
Output Level		"Zero" Level "One" Level	90% V _{DD}		10% V _{DD}	V	
Input Requirements for Pin 1		"1": On-Pin 1 may float or 90% V _{DD} min. "0": Tristate-Pin 1 requires 10% V _{DD}					



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Environmental and Mechanical Conditions

Parameter	Condition
Storage Temperature	-55°C to +150°C
Shock	1000 Gs, 0.35 ms, ½ sine wave, 3 shocks in each plane
Vibration	10-2000 Hz of 0.06" d.a. or 20Gs, whichever is less
Humidity	Resistant to 85° R.H. at 85°C
Leak	Per MIL-STD-883, Method 1014, Cond. A1 and Cond. C
Case	Hermetically sealed ceramic LCC
Pads	15 microinch of gold over nickel
Resistance to Solvents	Per MIL-STD-202, Method 215
Marking	Epoxy ink or laser engraved

FIXED OUTPUT	TRISTATE	Operating Temperature	Frequency Stability
Model	Model		
VFH2321	VFH2421	-55°C to +85°C	±25 ppm
VFH2322	VFH2422	-55°C to +85°C	±50 ppm
VFH2323	VFH2423	-55°C to +125°C	±75 ppm
VFH2324	VFH2424	-55°C to +125°C	±50 ppm

Table 1

Each unit undergoes the following:

- | | |
|--|---|
| 1. Stabilization Bake | MIL-STD-883 Method 1008, Cond.,B |
| 2. Temperature Cycling | MIL-STD-883 Method 1010, Cond, B |
| 3. Constant Acceleration | MIL-STD-883 Method 2001, Cond, A |
| 4. Burn-in | MIL-STD-883 Method 1015, Cond B (125°C for 168 hours with bias) |
| 5. Fine Leak | MIL-STD-883 Method 1014, Cond. A1 |
| 6. Gross Leak | MIL-STD-883 Method 1014, Cond C |
| 7. Electrical Test at 25°C and temperature extremes, as follows: | |
| A. Frequency | F. Duty Cycle |
| B. Current | G. Frequency at max V _{DD} |
| C. Rise Time | H. Frequency at min V _{DD} |
| D. Fall Time | I. "Zero" logic level |
| E. Duty Cycle | J. Tristate |

Test Data on each unit is available for additional cost

Thermal Characteristics

Thermal Resistance

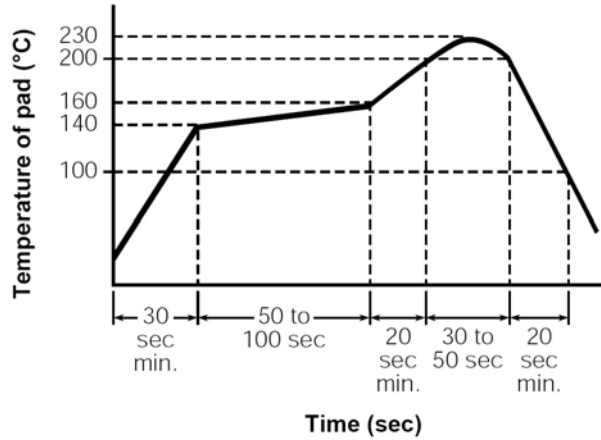
From Junction to Case, R_{θjc} 16 °C/Watt

Surface Mount Application

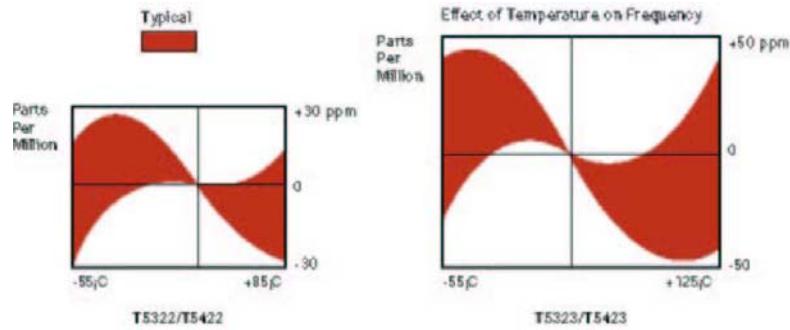
These packages are designed for reflow soldering in accordance with recommended profiles. For hand-soldering, the temperature of the iron should not exceed 400°C for three seconds.



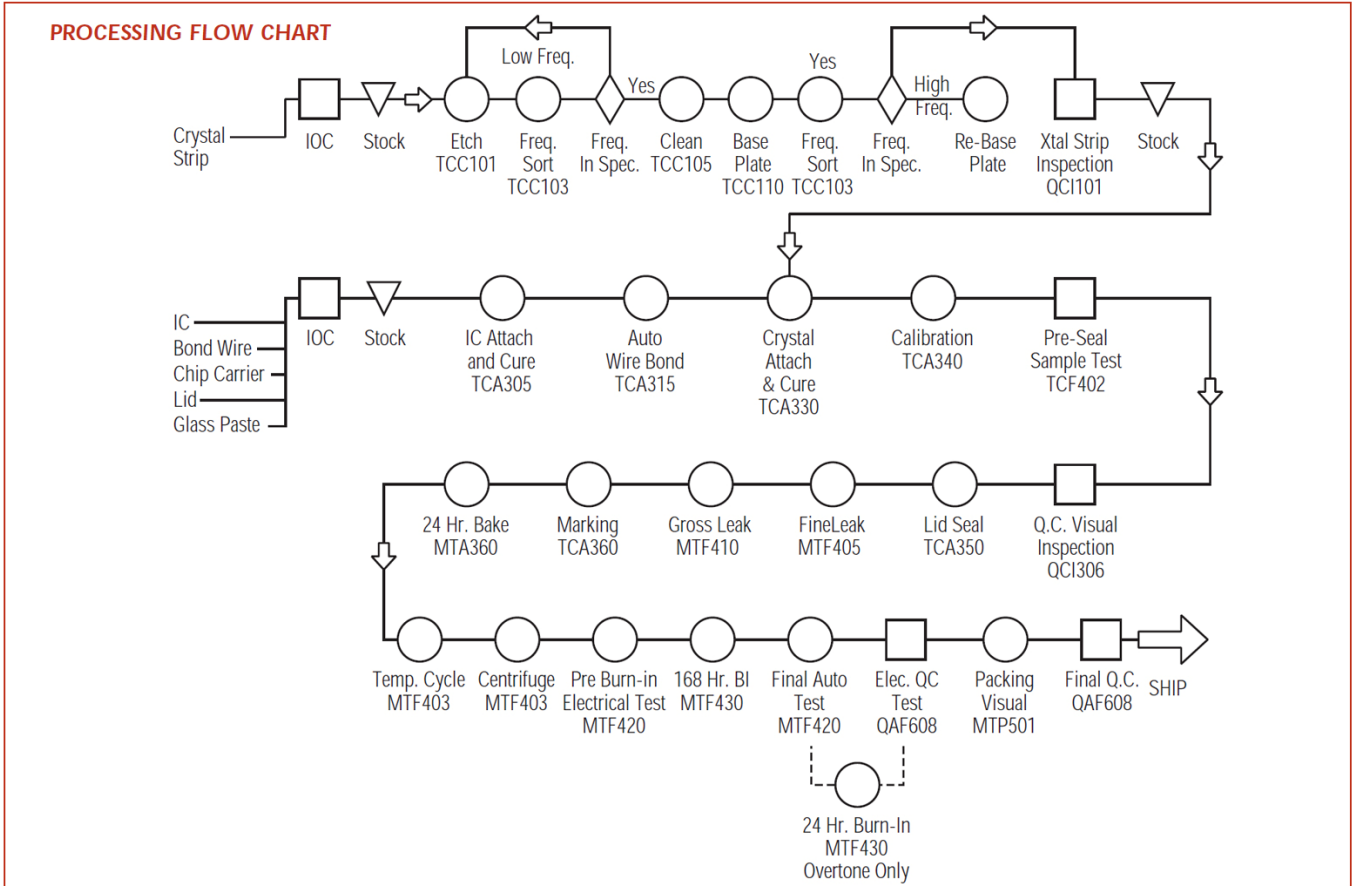
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Recommended Reflow Soldering Profile



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TABLE 2
Reliability Test Procedures and Conditions for Quartz Crystal Oscillators

1. Group A

Electrical Characteristics at -55°C, and 125°C
 (85°C for VFH2321, VFH2421, VFH2322, VFH2422)
 Frequency @ 1.7, 1.8, and 1.9 volts
 Symmetry (Duty Cycle)
 Input current
 Zero/One levels
 Rise/Fall times
 Physical Dimensions
 Length/width
 Height
 Seal (Visual)
 Package finish (Corrosion, discoloration, etc.)
 Marking placement/legibility

2. Group B- Life Test

1000 hrs at or above 125°C, 1.8V VDC, with proper load

3. Group C- All units have passed Group A testing

A. Subgroup 1-8 pcs.

<u>Standard</u>	<u>Condition</u>	<u>Description</u>	<u>End Point Measurement</u>
MIL-STD-883	Method 2002 COND.B	Mechanical Shock 1500 g's, 0.5ms 5 drops, 6 axis	Frequency Output waveform
MIL-STD-883	Method 2007 COND. A.	Vibration, var. freq. 20 g's, 0.06" disp., 20- 20, 000-20 Hz	Frequency Output waveform
MIL-STD-883	Method 2003	Solderability	Visual 95% Coverage

B. Subgroup 2-4 pcs (One-half of Subgroup 1)

<u>Standard</u>	<u>Condition</u>	<u>Description</u>	<u>End point Measurement</u>
MIL-STD-883	Method 1011 COND. B	Thermal Shock Liq. To liq. -55°C to 125°C, 15 cycles	Frequency Output waveform
MIL-STD-202	Method 105 COND. B	Altitude, 3.44 inch Hg. 12 hrs	Frequency Output waveform
MIL-STD-883	Method 1004	Moisture resist. with 1.8V applied 25°C to 65°C, 90 to 100% RH, 10 cycles	Frequency Output waveform
MIL-STD-202	Method 210 COND.A	Resistance to Solder Heat Immersion @350°C 3.5 sec	Frequency Output waveform

C. Subgroups 3-4 pcs. (One half of Subgroup 1)

<u>Standard</u>	<u>Condition</u>	<u>Description</u>	<u>End point Measurement</u>
	Storage Temp. No. Oper	24 hrs. @ -55°C 24 hrs. @ 125°C	Frequency Output waveform
MIL-STD-883	Method 1009 COND. A	Salt Atmosphere 24 hrs. @ 35°C 0.5-3.0% Solution	Frequency Output waveform Visual
MIL-STD-883	Method 1014 COND. A1	Fine Leak	Qs <5 X10 ⁻⁸
MIL-STD-883	Method 1014 COND. C1	Gross Leak	Visual in 125°C Detector fluid

